50 kPa On-Chip Temperature Compensated and Calibrated Silicon Pressure Sensors

The MPX2053 series devices are silicon piezoresistive pressure sensors that provide a highly accurate and linear voltage output directly proportional to the applied pressure. A single, monolithic silicon diaphragm with the strain gauge and an integrated thin-film resistor network. Precise span and offset calibration with temperature compensation are achieved by laser trimming.

Features

- Temperature Compensated Over 0°C to +85°C
- Easy-to-Use Chip Carrier Package Options
- Ratiometric to Supply Voltage
- Gauge Ported and Non Ported Options
- Available in Easy-to-Use Tape & Reel
- Differential and Gauge Pressure Options

MPX2053 Series

0 to 50 kPa (0 to 7.25 psi) 40 mV Full Scale (Typical)

Application Examples

- Pump/Motor Control
- Robotics
- Level Detectors
- Medical Diagnostics
- Pressure Switching
- Blood Pressure Measurement

ORDERING INFORMATION								
Device Name	Case No. # of Ports			Pressure Type			Device Marking	
		None	Single	Dual	Gauge	Differential	Absolute	Device warking
Small Outline Pac	kage (MPXV)	2053G Se	ries)					
MPXV2053GP	1369		•		•			MPXV2053GP
MPXV2053DP	1351			•		•		MPXV2053DP
Unibody Package	(MPX2053 S	eries)						
MPX2053D	344	•				•		MPX2053D
MPX2053DP	344C			٠		•		MPX2053DP
MPX2053GP	344B		•		•			MPX2053GP
MPAK Package (N	IPXM2053 Se	eries)						
MPXM2053D	1320	•				•		MPXM2053D
MPXM2053DT1	1320	•				•		MPXM2053D
MPXM2053GS	1320A		•		•			MPXM2053GS
MPXM2053GST1	1320A		•		•			MPXM2053GS



Pressure

UNIBODY PACKAGES



MPX2053D CASE 344-15





MPX2053DP CASE 344C-01

SMALL OUTLINE PACKAGES





MPXV2053GP CASE 1369-01

MPXV2053DP CASE 1351-01

MPAK PACKAGES

MPXM2053D/DT1 CASE 1320-02



MPXM2053GS/GST1 CASE 1320A-02

Operating Characteristics

Table 1. Operating Characteristics (V_S = 10 V_{DC}, T_A = 25°C unless otherwise noted, P1 > P2)

Characteristic	Symbol	Min	Тур	Max	Units
Pressure Range ⁽¹⁾	P _{OP}	0	—	50	kPa
Supply Voltage ⁽²⁾	V _S	_	10	16	V _{DC}
Supply Current	Ι _ο		6.0	_	mAdc
Full Scale Span ⁽³⁾	V _{FS}	38.5	40	41.5	mV
Offset ⁽⁴⁾	_	-1.0	—	1.0	mV
Sensitivity	—	ΔV/ΔΡ	—	0.8	—
Non-Linearity	_	-0.6	_	0.4	%V _{FS}
Pressure Hysteresis (0 to 50 kPa)	_		±0.1		%V _{FS}
Temperature Hysteresis (-40° to 125°C)	_		±0.5		%V _{FS}
Temperature Coefficient of Full Scale	TCV _{FS}	-2.0	_	2.0	%V _{FS}
Temperature Coefficient of Offset	TCV _{OFF}	-1.0	_	1.0	mV
Input Impedance	Z _{IN}	1000	_	2500	Ω
Output Impedance	Z _{OUT}	1400	—	3000	Ω
Response Time ⁽⁵⁾ (10% to 90%)	t _R	_	1.0	_	ms
Warm-Up Time	—	_	20	_	ms
Offset Stability ⁽⁶⁾	_	—	±0.5	_	%V _{FS}

1. 1.0 kPa (kiloPascal) equals 0.145 psi.

2. Device is ratiometric within this specified excitation range. Operating the device above the specified excitation range may induce additional error due to device self-heating.

3. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.

4. Offset (V $_{\text{off}}$) is defined as the output voltage at the minimum rated pressure.

5. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.

6. Offset stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

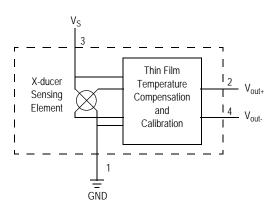
Maximum Ratings

Table 2. Maximum Ratings⁽¹⁾

Rating	Max Value	Unit
Supply Voltage	16	V
Pressure (P1 > P2)	200	kPa
Storage Temperature	-40 to +125	°C
Operating Temperature Range	-40 to +125	℃

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.





Voltage Output versus Applied Differential Pressure

The differential voltage output of the sensor is directly proportional to the differential pressure applied.

The output voltage of the differential or gauge sensor increases with increasing pressure applied to the pressure

side relative to the vacuum side. Similarly, output voltage increases as increasing vacuum is applied to the vacuum side relative to the pressure side.

On-Chip Temperature Compensation and Calibration

Figure 2 shows the minimum, maximum and typical output characteristics of the MPX2053 series at 25°C. The output is directly proportional to the differential pressure and is essentially a straight line.

A silicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

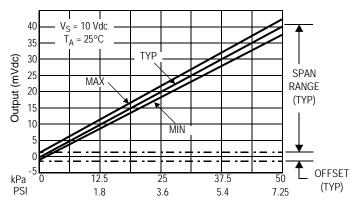


Figure 2. Output vs. Pressure Differential

LINEARITY

Linearity refers to how well a transducer's output follows the equation: $V_{out} = V_{off}$ + sensitivity x P over the operating pressure range. There are two basic methods for calculating nonlinearity: (1) end point straight line fit (see Figure 3) or (2) a least squares best line fit. While a least squares fit gives the "best case" linearity error (lower numerical value), the calculations required are burdensome. Conversely, an end point fit will give the "worst case" error (often more desirable in error budget calculations) and the calculations are more straightforward for the user. The specified pressure sensor linearities are based on the end point straight line method measured at the midrange pressure.

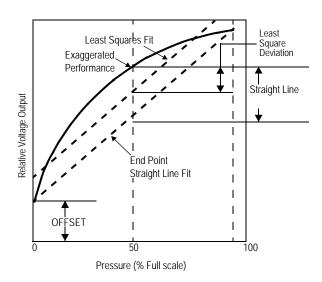


Figure 3. Linearity Specification Comparison

Figure 4 illustrates the differential or gauge configuration in the basic chip carrier (Case 344). A silicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

The MPX2053 series pressure sensor operating characteristics and internal reliability and qualification tests

are based on use of dry air as the pressure media. Media other than dry air may have adverse effects on sensor performance and long term reliability. Contact the factory for information regarding media compatibility in your application. Refer to application note AN3728, for more information regarding media compatibility.

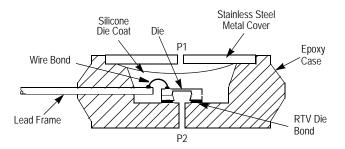
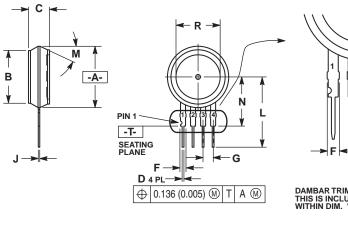
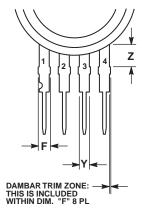


Figure 4. Unibody Package — Cross-Sectional Diagram (Not to Scale)





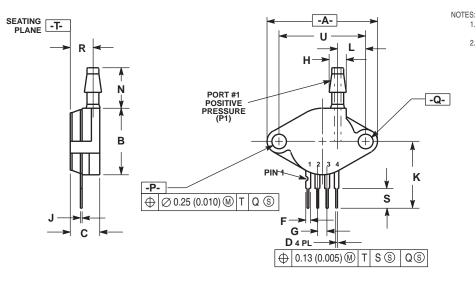
NOTES:		
4	DIMENCIONING	ANIE

DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: INCH.
 DIMENSION -A- IS INCLUSIVE OF THE MOLD STOP RING. MOLD STOP RING NOT TO EXCEED 16.00 (0.630).

	INC	HES	MILLIM	ETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.595	0.630	15.11	16.00	
В	0.514	0.534	13.06	13.56	
С	0.200	0.220	5.08	5.59	
D	0.016	0.020	0.41	0.51	
F	0.048	0.064	1.22	1.63	
G	0.100) BSC	2.54 BSC		
J	0.014	0.016	0.36	0.40	
L	0.695	0.725	17.65	18.42	
М	30° NOM		30° I	NOM	
Ν	0.475	0.495	12.07	12.57	
R	0.430	0.450	10.92	11.43	
Y	0.048	0.052	1.22	1.32	
Z	0.106	0.118	2.68	3.00	

2.	ground + output + supply		GND -VOUT VS
	+ SUPPLY - OUTPUT	+ SUPPLY GROUND	VS +VOUT

CASE 344-15 **ISSUE AA UNIBODY PACKAGE**



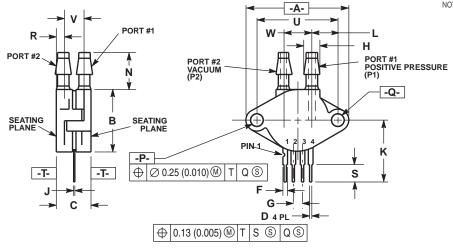
DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

2. CONTROLLING DIMENSION: INCH.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	1.145	1.175	29.08	29.85
В	0.685	0.715	17.40	18.16
С	0.305	0.325	7.75	8.26
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.10) BSC	2.54	BSC
Н	0.182	0.194	4.62	4.93
J	0.014	0.016	0.36	0.41
κ	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
Ν	0.420	0.440	10.67	11.18
Р	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.230	0.250	5.84	6.35
S	0.220	0.240	5.59	6.10
U	0.910) BSC	23.11	I BSC

STYLE 1: PIN 1. GROUND 2. + OUTPUT 3. + SUPPLY 4. - OUTPUT

CASE 344B-01 **ISSUE B UNIBODY PACKAGE**

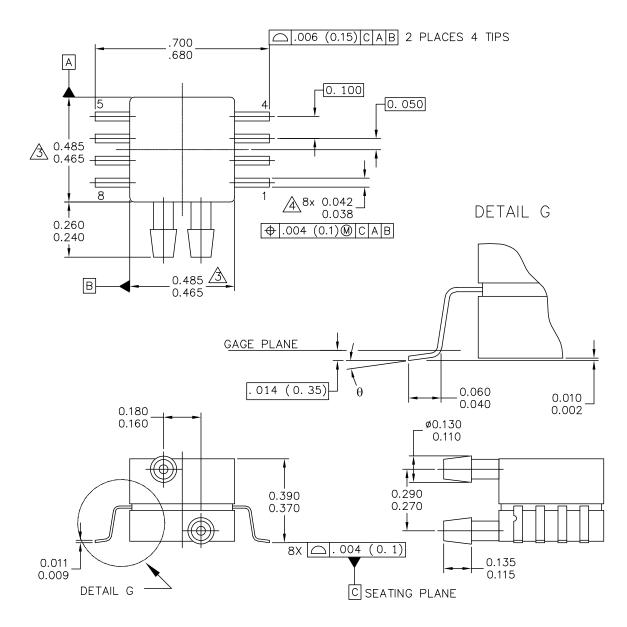


NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	INC	IES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	1.145	1.175	29.08	29.85
В	0.685	0.715	17.40	18.16
С	0.405	0.435	10.29	11.05
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100	BSC	2.54	BSC
н	0.182	0.194	4.62	4.93
J	0.014	0.016	0.36	0.41
ĸ	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
Р	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.063	0.083	1.60	2.11
S	0.220	0.240	5.59	6.10
U	0.910	BSC	23.1	1 BSC
V	0.248	0.278	6.30	7.06
W	0.310	0.330	7.87	8.38

STYLE 1: PIN 1. GROUND 2. + OUTPUT 3. + SUPPLY 4. - OUTPUT

CASE 344C-01 **ISSUE B UNIBODY PACKAGE**



© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.		LOUTLINE	PRINT VERSION NO	DT TO SCALE
TITLE:		DOCUMENT NO): 98ASA99255D	REV: A
8 LD SNSR. DUAL	PORT	CASE NUMBER	8: 1351–01	27 JUL 2005
		STANDARD: NO	N-JEDEC	

PAGE 1 OF 2

CASE 1351-01 ISSUE A SMALL OUTLINE PACKAGE

NOTES:

1. CONTROLLING DIMENSION: INCH

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PPROTRUSIONS. MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 PER SIDE.

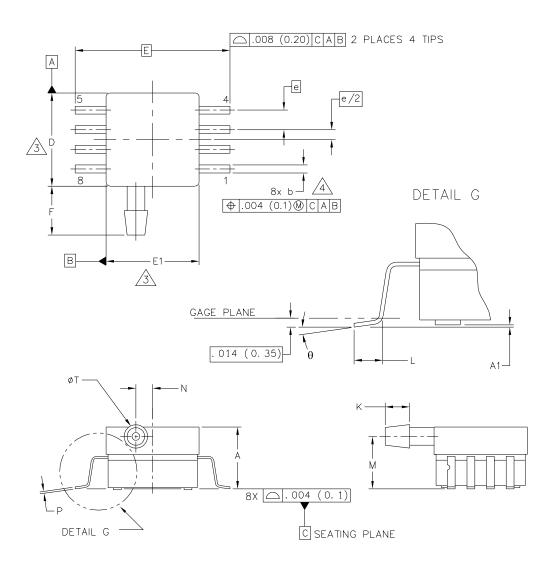
A DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

STYLE 1:		STYLE 2:		
PIN 1:	GND	PIN	1:	N/C
PIN 2:	+Vout	PIN	2:	Vs
PIN 3:	Vs	PIN	3:	GND
PIN 4:	-Vout	PIN	4:	Vout
PIN 5:	N/C	PIN	5:	N/C
PIN 6:	N/C	PIN	6:	N/C
PIN 7:	N/C	PIN	7:	N/C
PIN 8:	N/C	PIN	8:	N/C

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.		LOUTLINE	PRINT VERSION NO	DT TO SCALE
TITLE:		DOCUMENT NO): 98ASA99255D	REV: A
8 LD SNSR, DUAL	PORT	CASE NUMBER	2: 1351–01	27 JUL 2005
		STANDARD: NO	N-JEDEC	

PAGE 2 OF 2

CASE 1351-01 ISSUE A SMALL OUTLINE PACKAGE



© FREESCALE SEMICONDUCTOR, INC. All RIGHTS RESERVED. MECHANIC		L OUTLINE	PRINT VERSION NO	DT TO SCALE
TITLE: 8 LD SOP. SIDE PORT		DOCUMENT NO): 98ASA99303D	REV: D
		CASE NUMBER	8: 1369-01	13 DEC 2010
	STANDARD: NO	N-JEDEC		

PAGE 1 OF 2

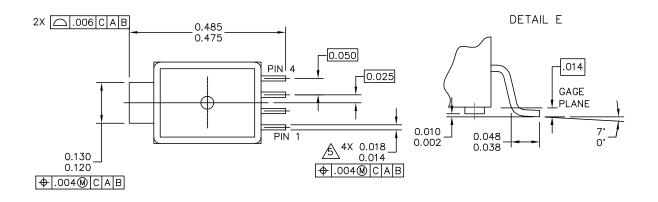
CASE 1369-01 ISSUE D SMALL OUTLINE PACKAGE

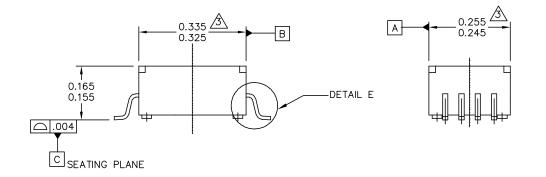
- NOTES: 1. CONTROLLING DIMENSION: INCH
- 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
- \underline{A} dimensions do not include Mold Flash or pprotrusions. MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 (0.152) PER SIDE.
- $\underline{\mathbb{A}}$ dimension does not include dambar protrusion. Allowable dambar PROTRUSION SHALL BE .008 (0.203) MAXIMUM.

	INCHES		MIL	LIMETERS		IN	NCHES	MI	LLIMETERS
DIM	MIN	MAX	MIN	MAX	DIM	Min	MAX	MIN	MAX
A	.300	.330	7.62	8.38	θ	0.	7.	0.	7.
A1	.002	.010	0.05	0.25	-				
b	.038	.042	0.96	1.07	-				
D	.465	.485	11.81	12.32	_				
E	.717	BSC	18	3.21 BSC	-				
E1	.465	.485	11.81	12.32	-				
е	.100	BSC	2.	54 BSC	_				
F	.245	.255	6.22	6.47	_				
к	.120	.130	3.05	3.30	-				
L	.061	.071	1.55	1.80	-				
М	.270	.290	6.86	7.36	_				
N	.080	.090	2.03	2.28	-				
Р	.009	.011	0.23	0.28	-				
Т	.115	.125	2.92	3.17	-				
	© FREESCALE SEMICONDUCTOR, INC. MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE								
CIFREESCALE SEMICONDUCTOR, INC. MECHANICAL OUTLINE PRINT						PRINI VER	SIUN NO	JI IU SCALE	
TITI	TITLE:					DOCUMENT NO: 98ASA99303D REV: D			REV: D
8 LD SOP, SIDE PORT				CASE NUMBER: 1369-01 13 DEC			13 DEC 2010		
						NDARD: NO	N-JEDEC		

PAGE 2 OF 2

CASE 1369-01 **ISSUE D** SMALL OUTLINE PACKAGE





© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICA	LOUTLINE	IT TO SCALE	
TITLE:		DOCUMENT NE]: 98ARH99088A	RE∨: B
5 LD M-PAC		CASE NUMBER	₹: 1320-02	22 JUL 2005
		STANDARD: NO	IN-JEDEC	

PAGE 1 OF 2

CASE 1320-02 ISSUE B

NOTES:

1. DIMENSIONS ARE IN INCHES.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. DIMENSION DOES NOT INCLUDE MOLD FLASH OR PROTRUSION. MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006" PER SIDE.

4. ALL VERTICAL SURFACES TO BE 5' MAXIMUM.

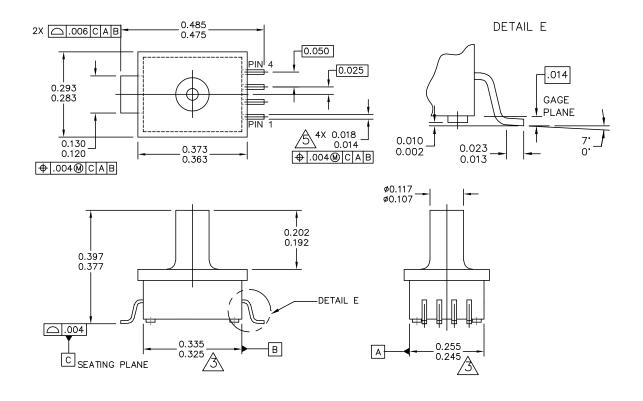
Allowable dambar protrusion shall be .008 Maximum.

PIN 1: GND PIN 2: +Vout PIN 3: Vs PIN 4: -Vout

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICA	MECHANICAL OUTLINE PRINT VERSION NOT		DT TO SCALE
TITLE:		DOCUMENT NO): 98ARH99088A	REV: B
5 LD M-PAC		CASE NUMBER	8: 1320–02	22 JUL 2005
		STANDARD: NO	N-JEDEC	

PAGE 2 OF 2

CASE 1320-02 ISSUE B



© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUT	LINE PRINT VERSIO	ON NOT TO SCALE
TITLE:	DOCU	MENT NO: 98ARH99087A	REV: A
5 LD M-PAC, PORTED		NUMBER: 1320A-02	22 JUL 2005
	STAN	IDARD: NON-JEDEC	

PAGE 1 OF 2

CASE 1320A-02 ISSUE A



NOTES:

1. DIMENSIONS ARE IN INCHES.

- 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
- A DIMENSIONS DOES NOT INCLUDE MOLD FLASH OR PROTRUSION. MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006" PER SIDE.
- 4. ALL VERTICAL SURFACES TO BE 5" MAXIMUM.
- 5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICA	AL OUTLINE PRINT VERSION NOT TO SCALE		
TITLE:	DOCUMENT NO): 98ARH99087A	REV: A	
5 LD M-PAC, POR	CASE NUMBER	R: 1320A-02	22 JUL 2005	
	STANDARD: NO	N-JEDEC		

PAGE 2 OF 2

CASE 1320A-02 ISSUE A

Table 3. Revision History

-	ision nber	Revision date	Description of changes
9	9	10/2012	Deleted references to device number MPXV2053GVP throughout the document

How to Reach Us:

Home Page: freescale.com

Web Support: freescale.com/support Information in this document is provided solely to enable system and software implementers to use Freescale products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits based on the information in this document.

Freescale reserves the right to make changes without further notice to any products herein. Freescale makes no warranty, representation, or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale data sheets and/or specifications can and do vary in different applications, and actual performance may vary over time. All operating parameters, including "typicals," must be validated for each customer application by customer's technical experts. Freescale does not convey any license under its patent rights nor the rights of others. Freescale sells products pursuant to standard terms and conditions of sale, which can be found at the following address: freescale.com/salestermsandconditions.

Freescale, the Freescale logo, Energy Efficient Solutions logo, are trademarks of Freescale Semiconductor, Inc., Reg. U.S. Pat. & Tm. Off. Xtrinsic is a trademark of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners.

© 2012 Freescale Semiconductor, Inc.





Authorized Distribution Brand :



Website :

Welcome to visit www.ameya360.com

Contact Us :

➤ Address :

401 Building No.5, JiuGe Business Center, Lane 2301, Yishan Rd Minhang District, Shanghai , China

- > Sales :
 - Direct +86 (21) 6401-6692
 - Email amall@ameya360.com
 - QQ 800077892
 - Skype ameyasales1 ameyasales2

> Customer Service :

Email service@ameya360.com

> Partnership :

Tel +86 (21) 64016692-8333

Email mkt@ameya360.com